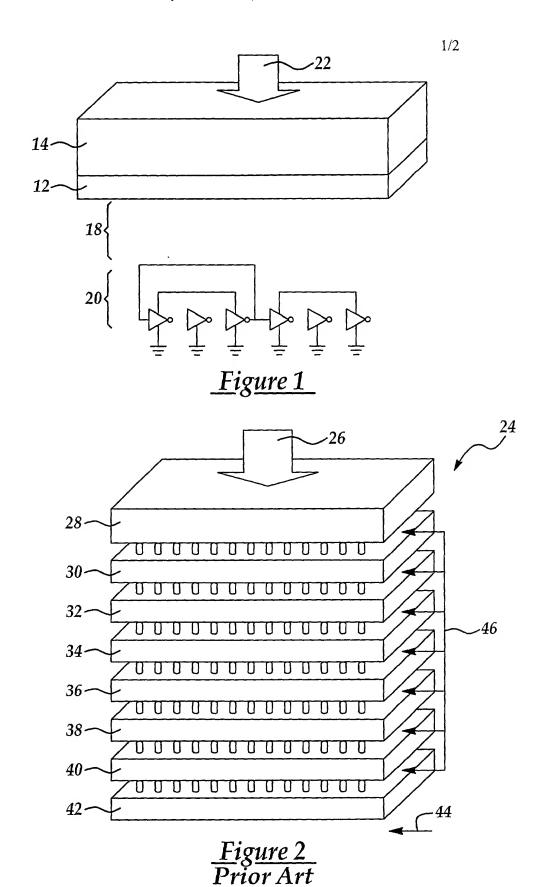
Inventor(s): Chou Serial No.: To Be Assigned Filed: Herewith

For: Single Layer Wiring Bond Pad With Optimum ... Under Pads

Attorney Docket No.: 67,200-603

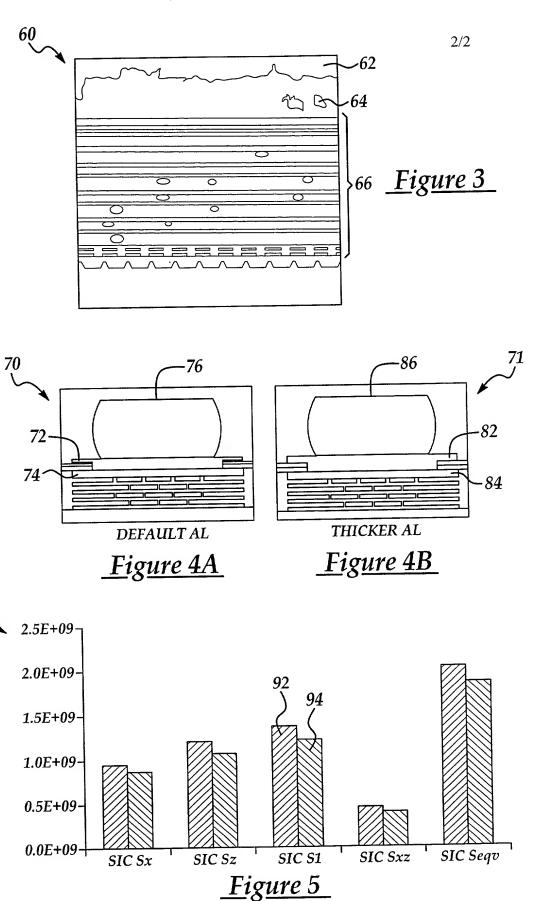


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